

# **Final Product Change Notification**

202306055F01: NVT4857UK New BOM Qualification at ASEK

Note: This notice is NXP Company

Proprietary.

Issue Date: Jul 12, 2023 Effective date:Oct 10, 2023

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#### **Management summary**

Changing of repassivation from PI to PBO on NVT4857UK at ASEK due to supplier discontinuation.

### **Change Category**

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Firmware	[]Other			

# **PCN** Overview

# Description

Changing of repassivation from PI to PBO on NVT4857UK at ASEK due to supplier discontinuation. Repassivation change before: I-8124ER1, and change after is: HD8820

UBM change before: Ti/NiV/Cu and change after is: Ti/Cu/Cu

It should be noted that the above configuration is a current standard and is in high volume manufacturing.

Note: A datasheet correction will be occurring. Package outline drawing (PoD) of the NVT4857UK was

renamed to SOT1397-10. Included in this update is a correction to the existing datasheet in which the

ball diameter was incorrectly listed. The correct ball diameter is being updated from 260 µm to reflect an

actual 270 µm (there were no change in products ball dimension).

#### Reason

Changing of repassivation from PI to PBO on NVT4857UK at ASEK due to supplier discontinuation.

#### **Identification of Affected Products**

Top Side Marking

## **Product Availability**

#### **Sample Information**

Samples are available upon request

#### **Production**

Planned first shipmentOct 16, 2023

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

**Data Sheet Revision** 

A new datasheet will be issued

**Disposition of Old Products** 

Existing inventory will be shipped until depleted

### Additional information

Self qualification: view online

## **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 11, 2023.

## **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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